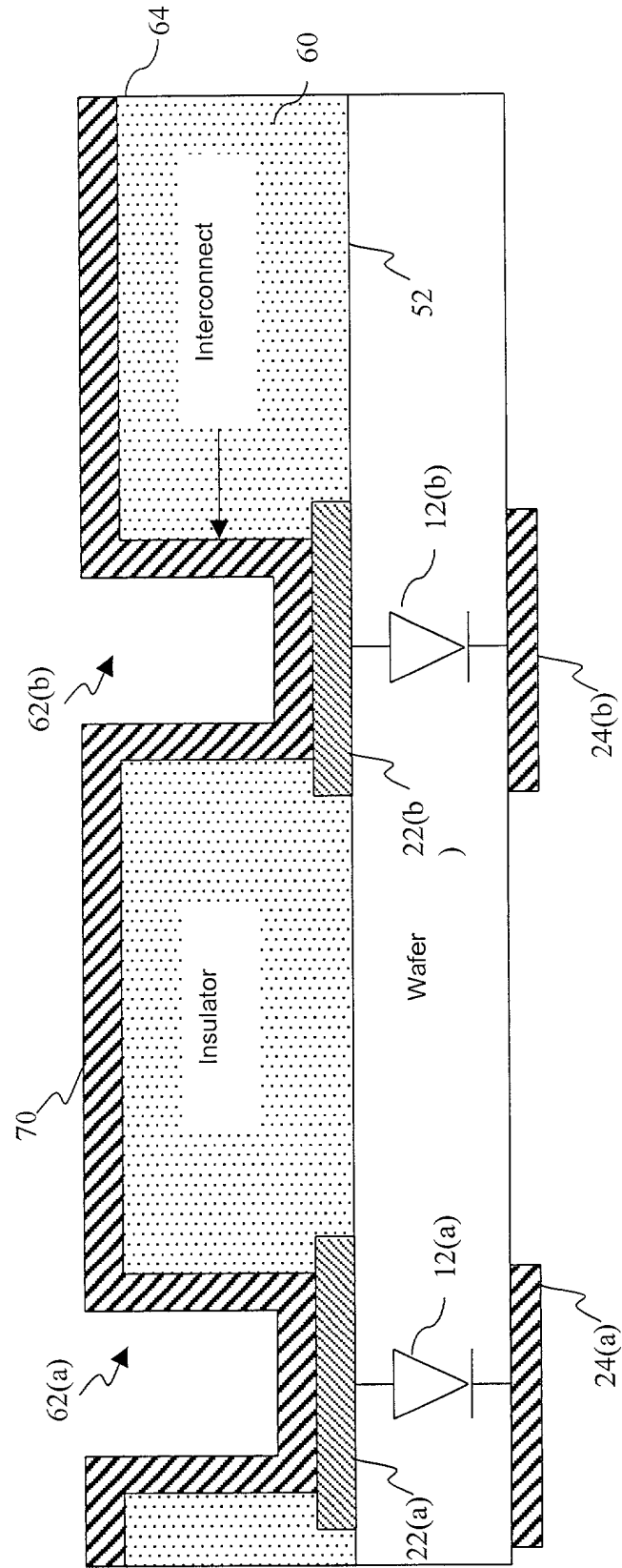


FIG. 2



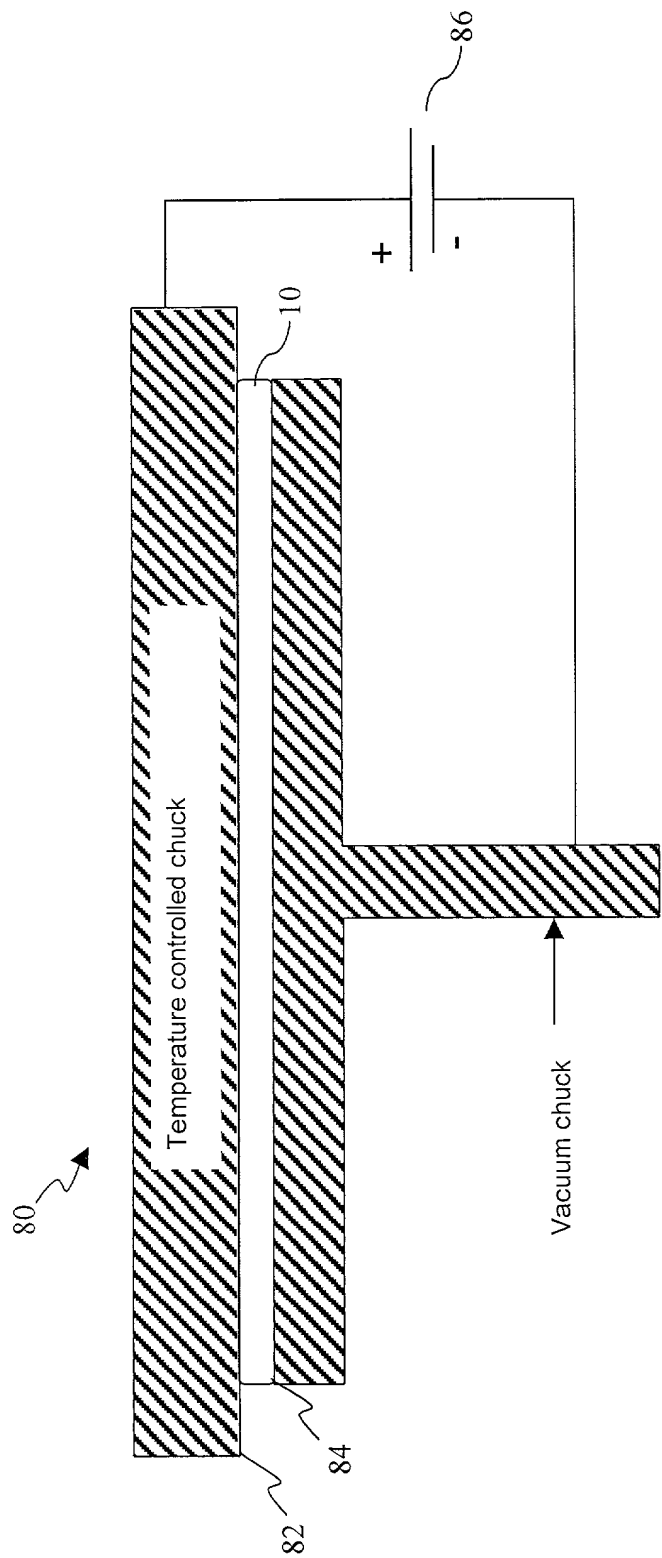
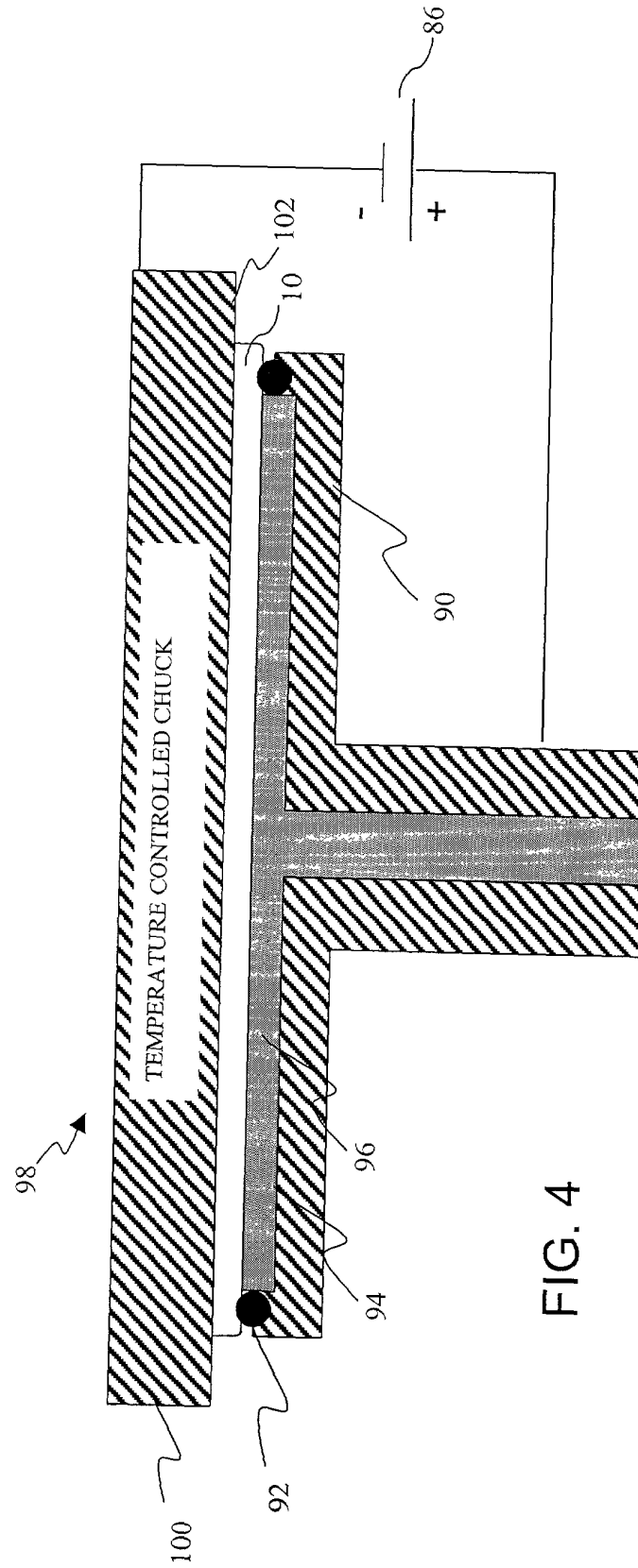
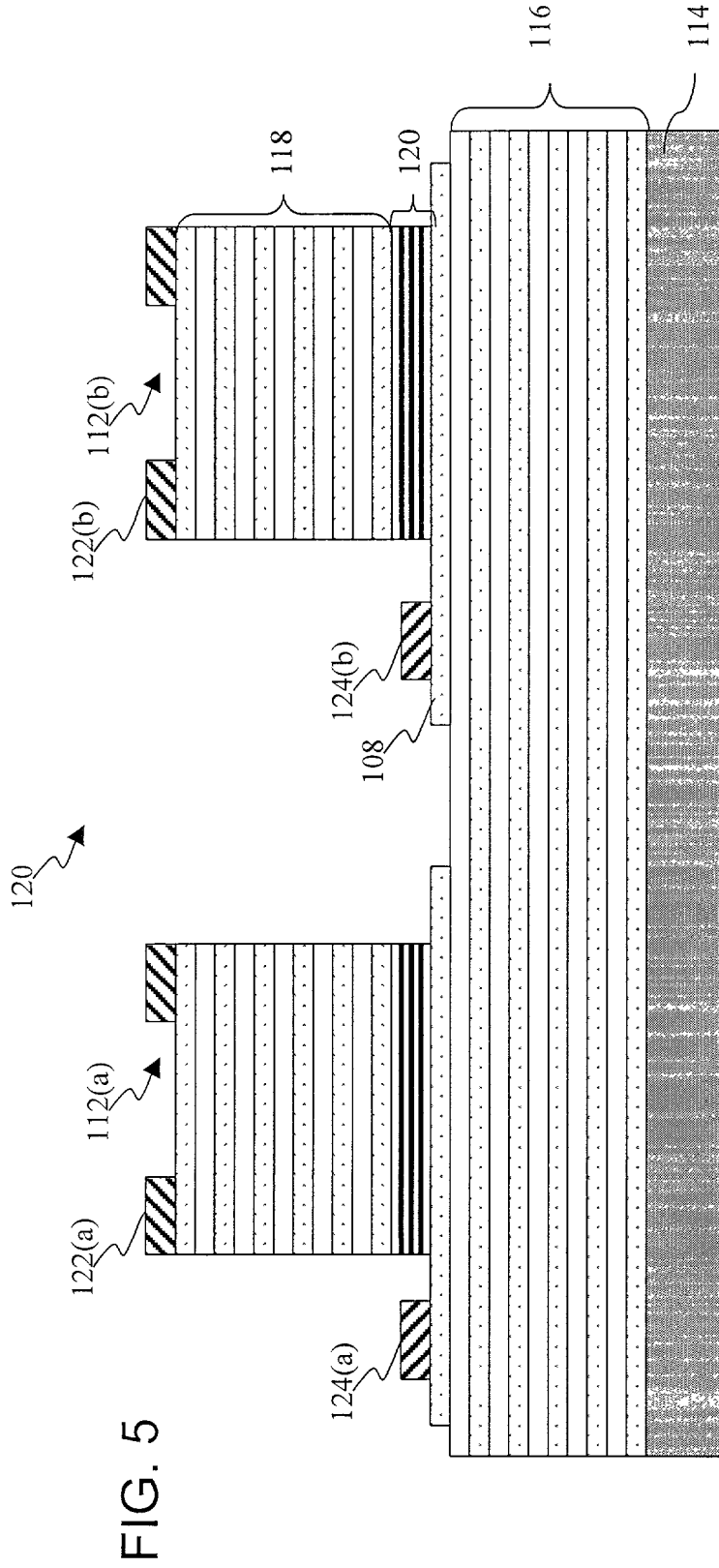


FIG. 3





[illegible]

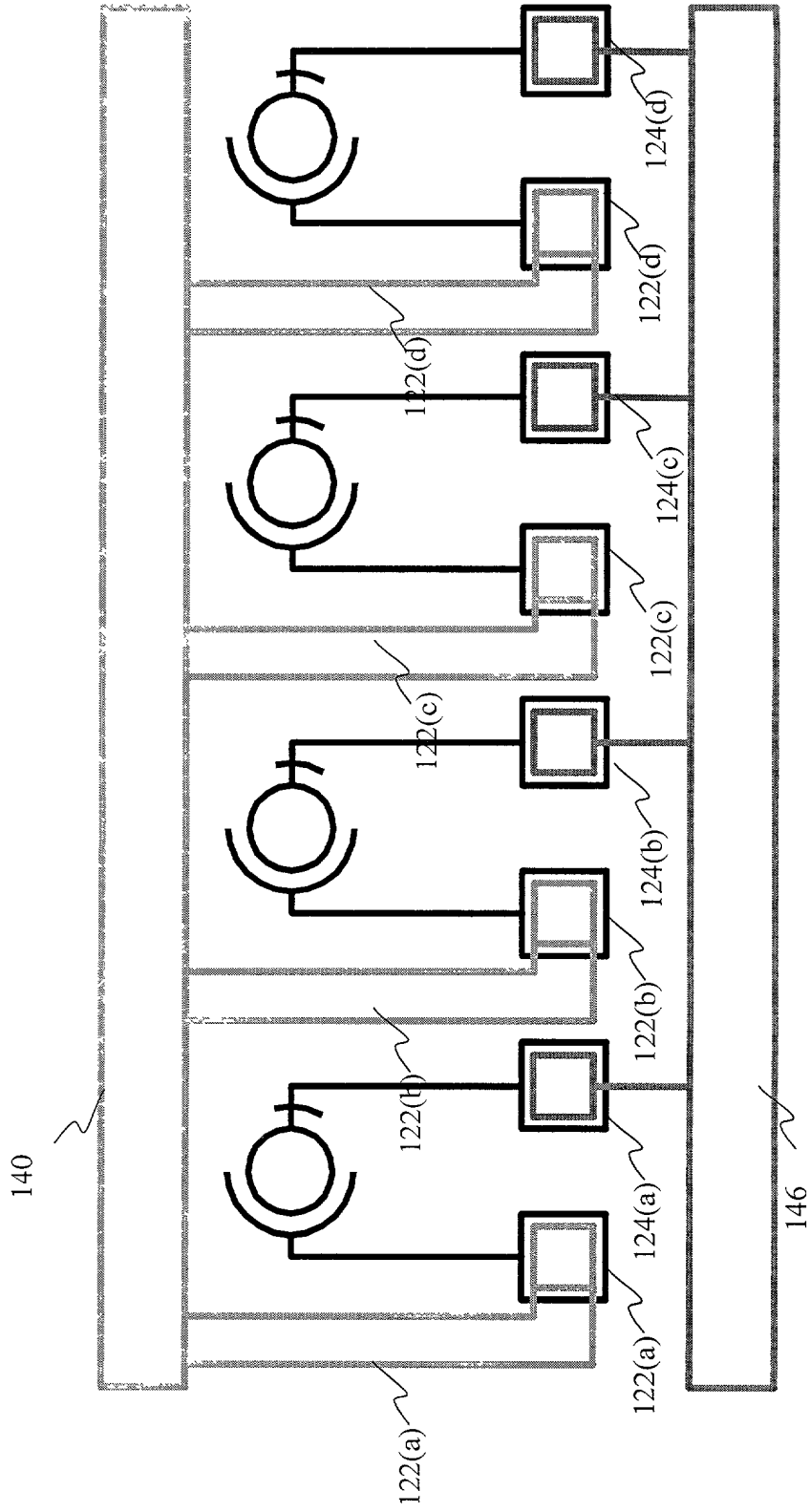


FIG. 7

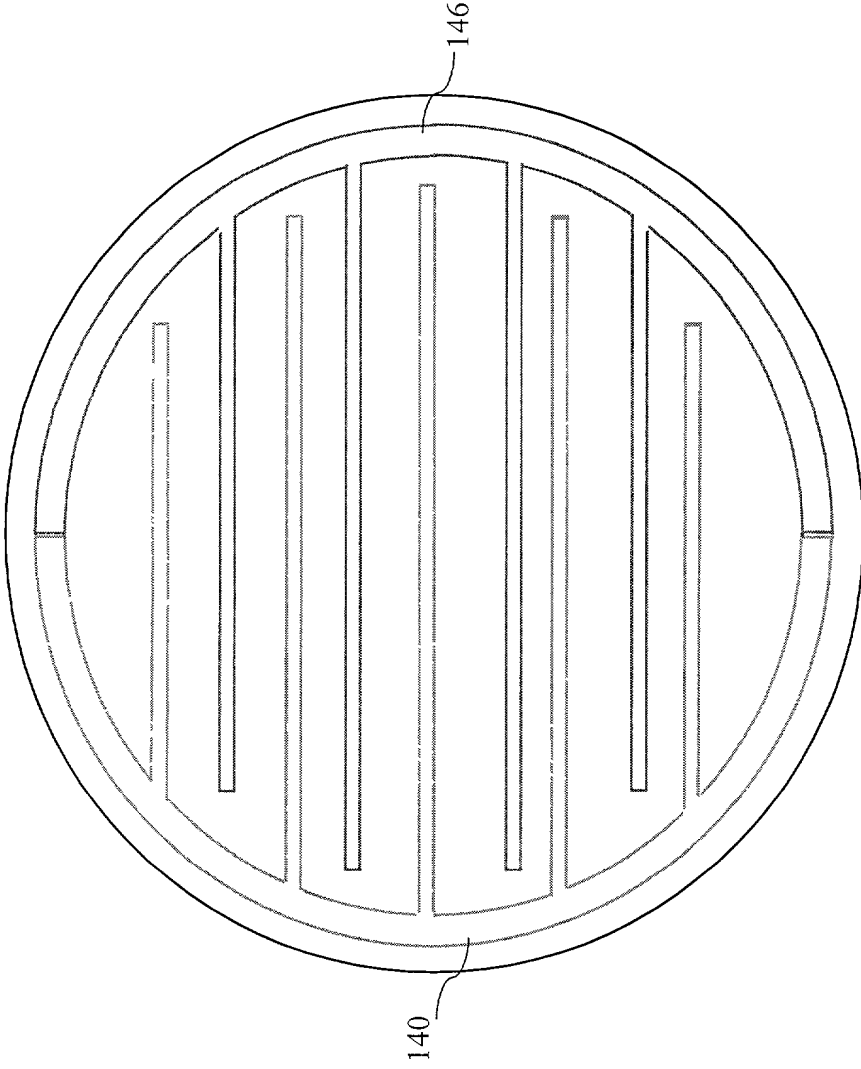
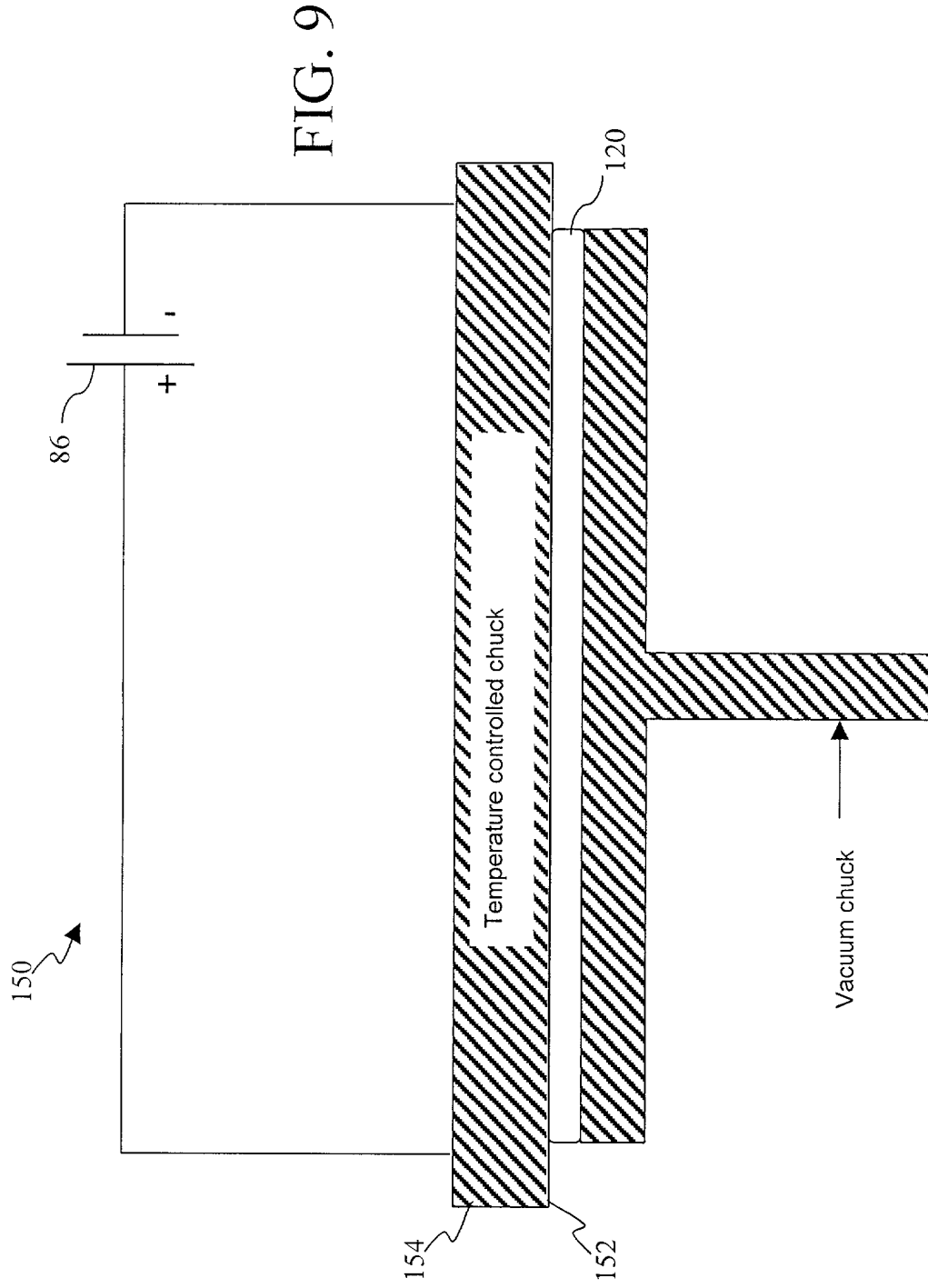


FIG. 8



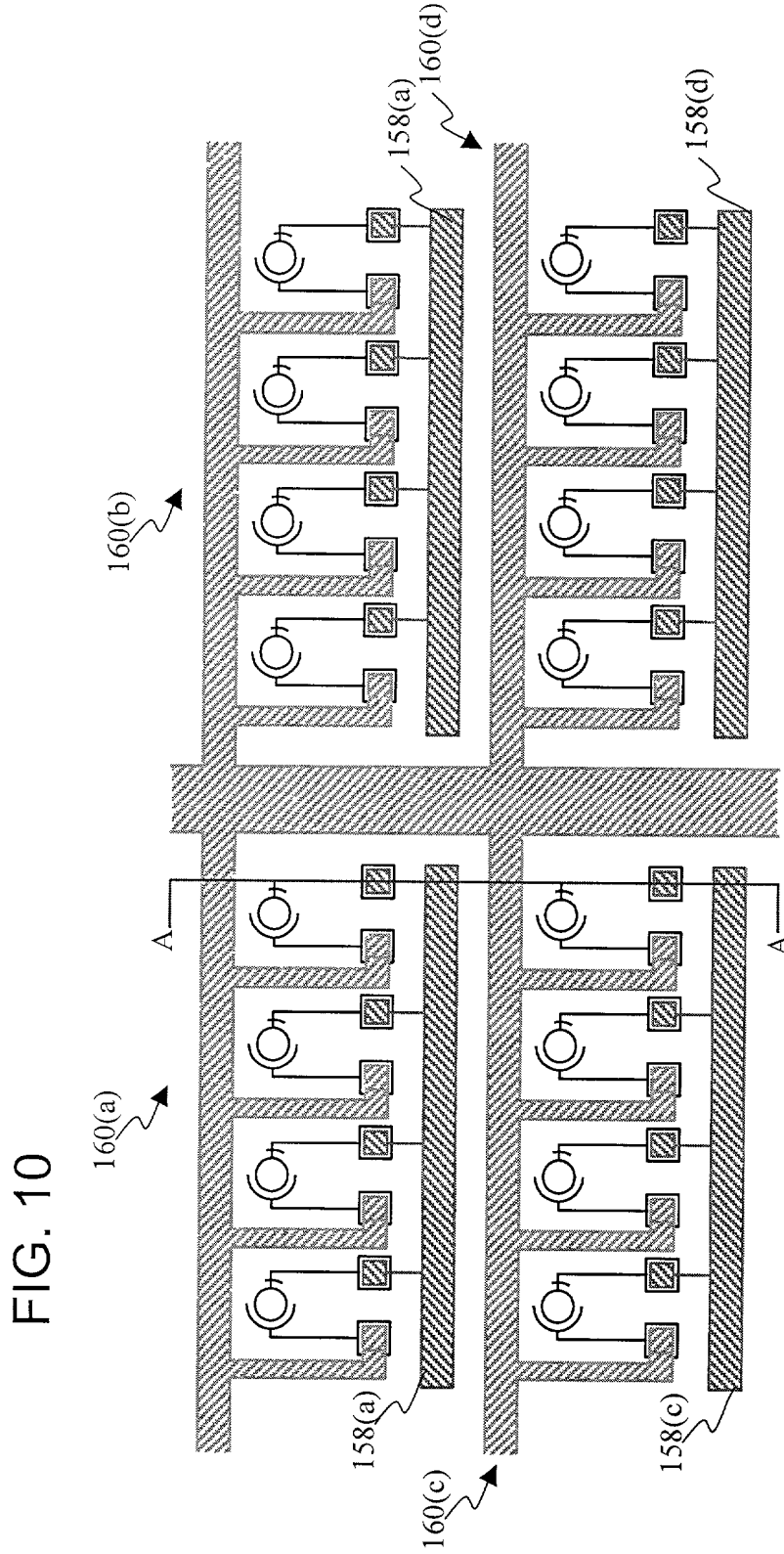


FIG. 11

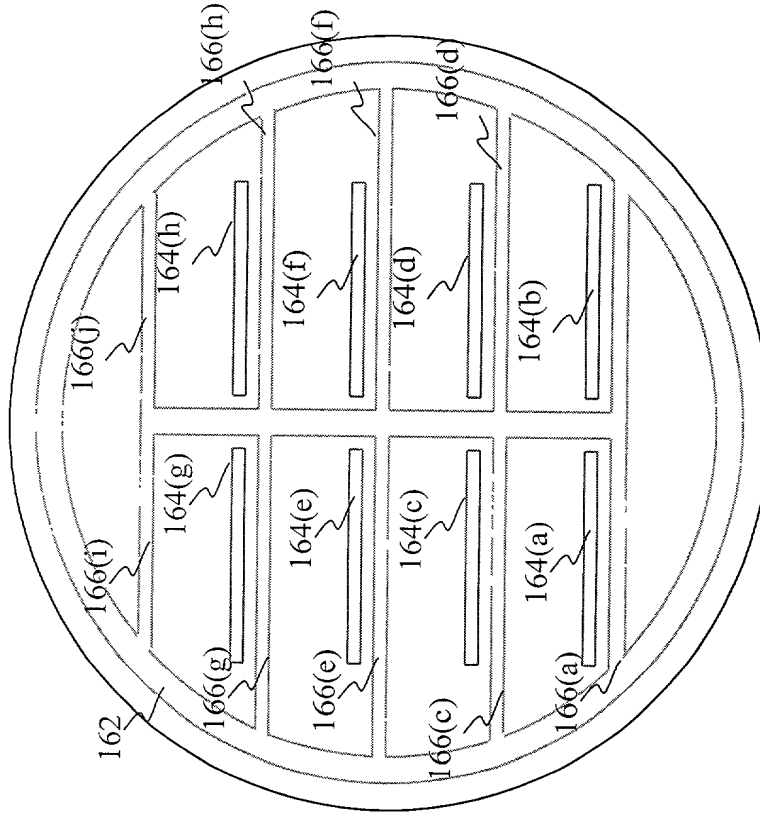
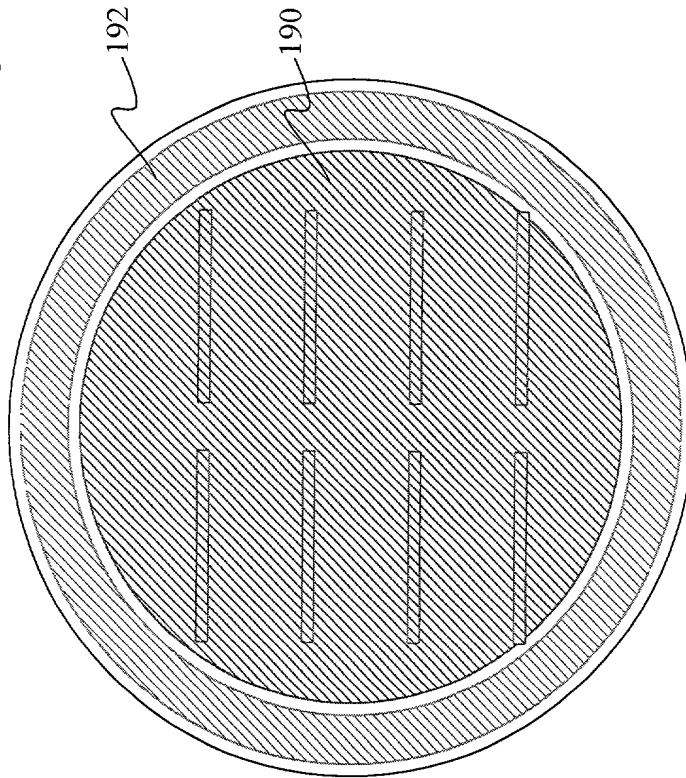


FIG. 13



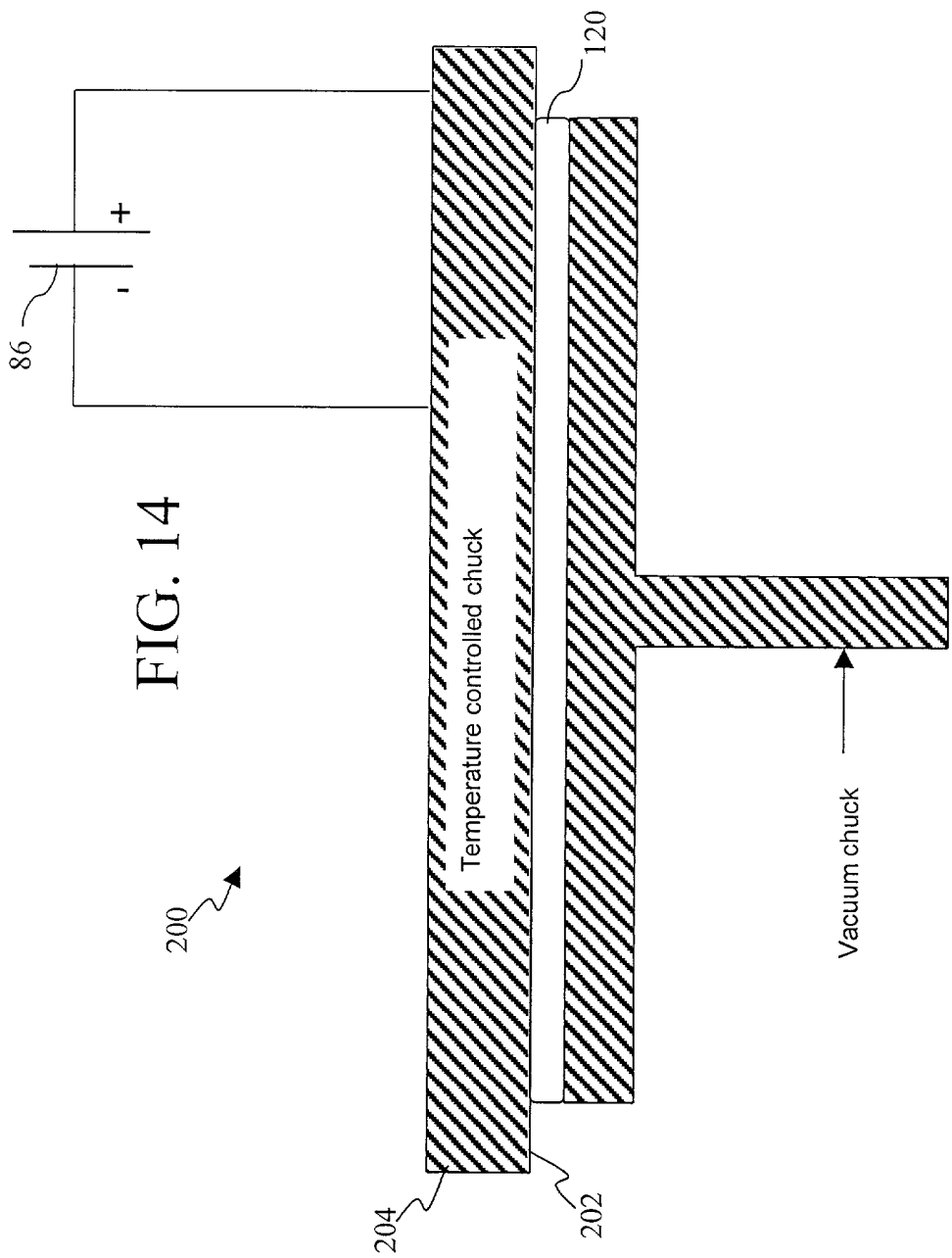
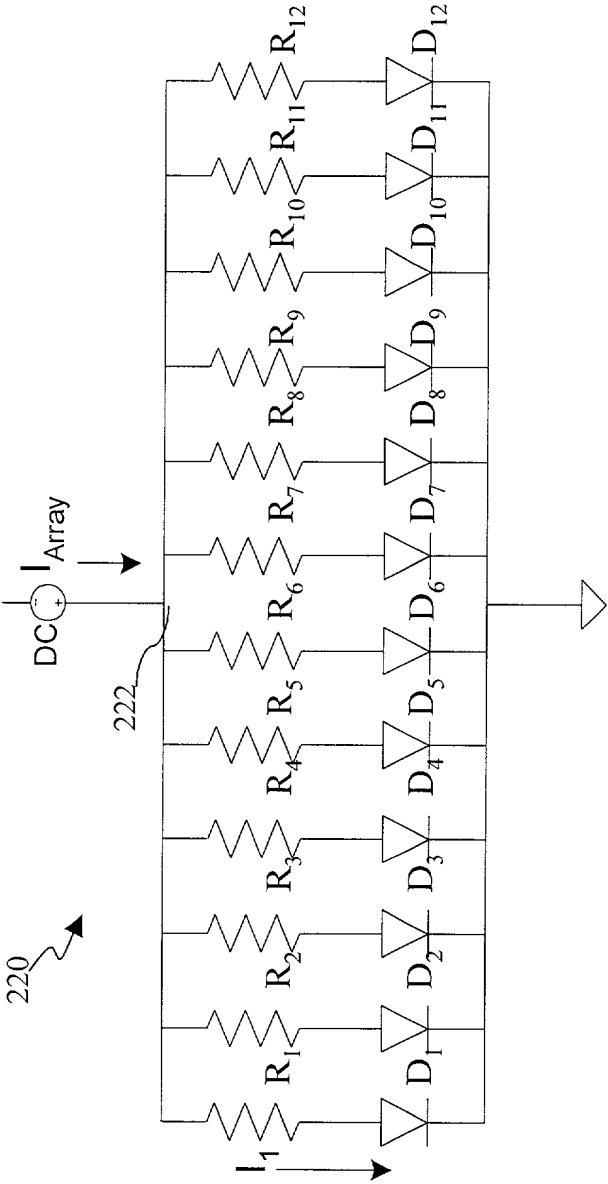


FIG. 15



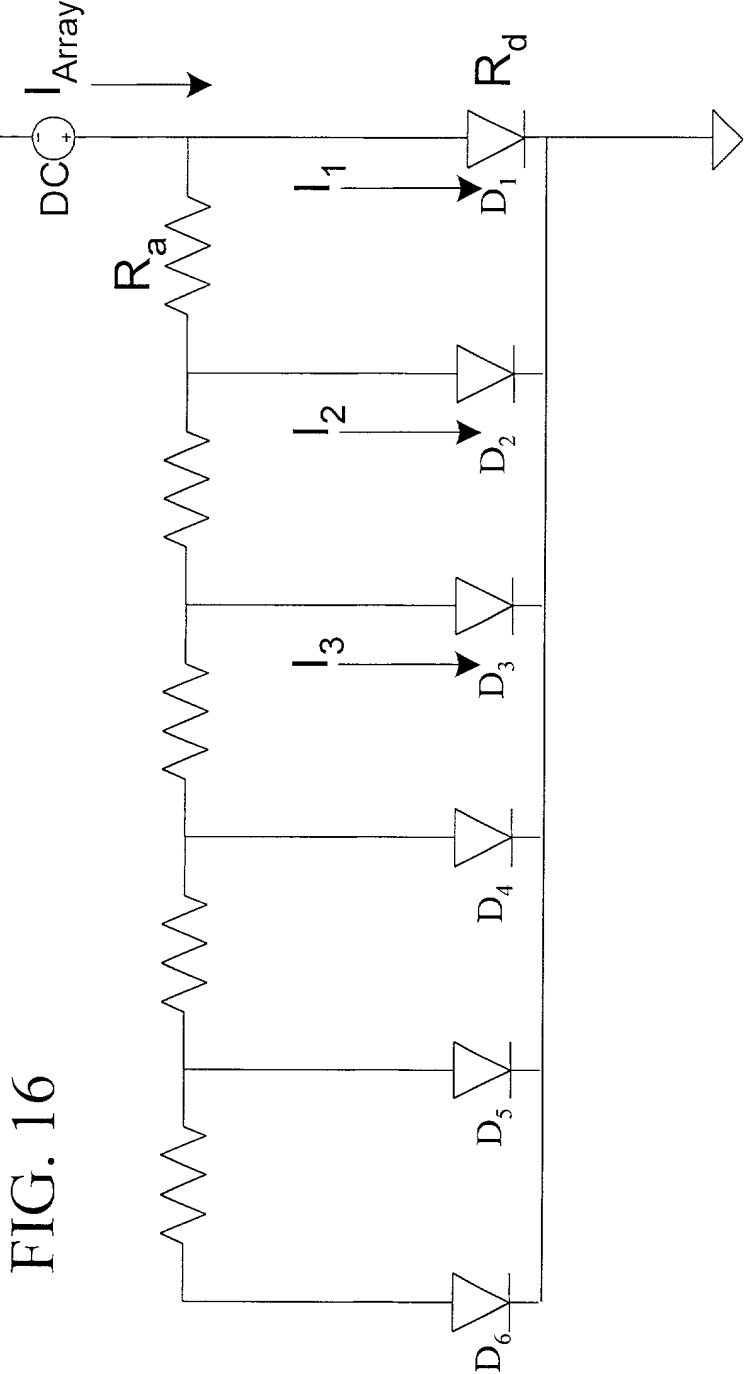


FIG. 16

FIG. 16 is a schematic diagram of a circuit for performing whole wafer burn-in. The circuit includes a DC current source I_{Array} connected to a series of resistors. The current through each resistor is indicated by I_1, I_2, I_3, \dots . The circuit also includes a series of diodes D_1, D_2, D_3, \dots connected in parallel to the resistors. A resistor R_d is connected to the output of the diodes, and the output is shown as a line with a triangle at the end.

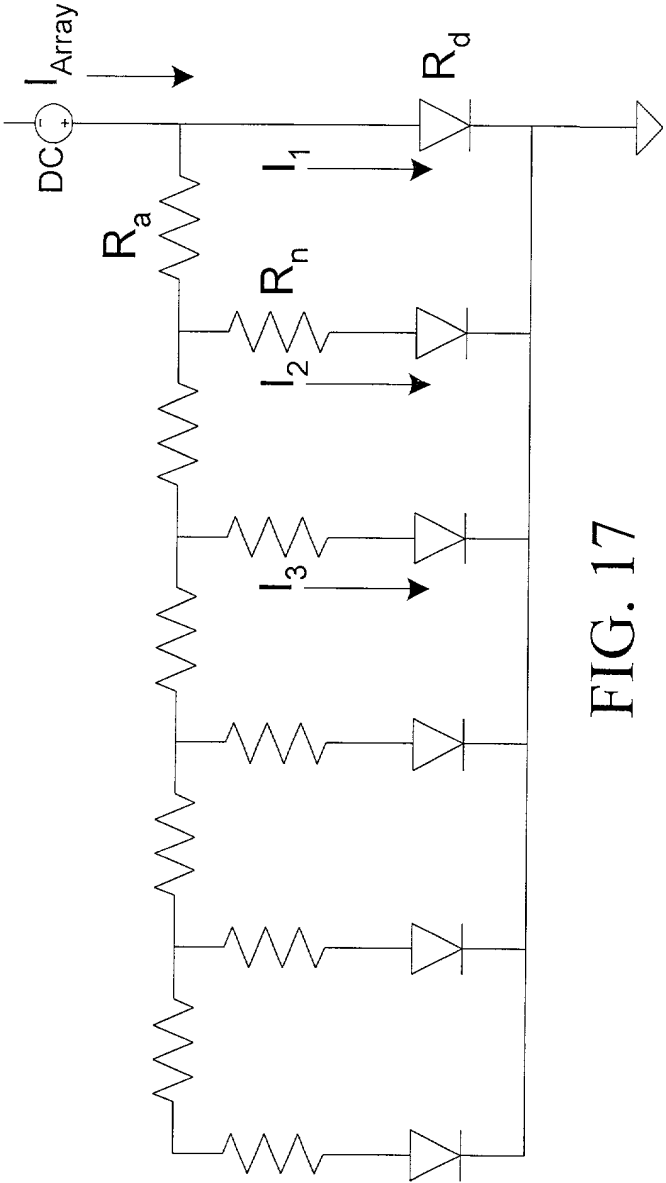
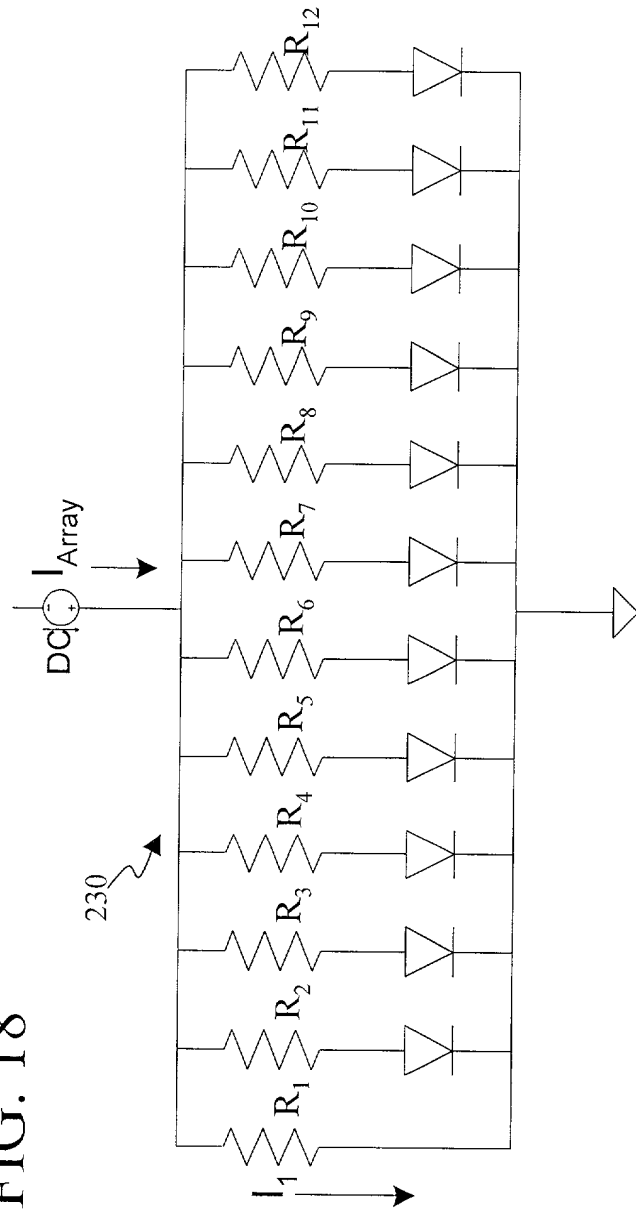
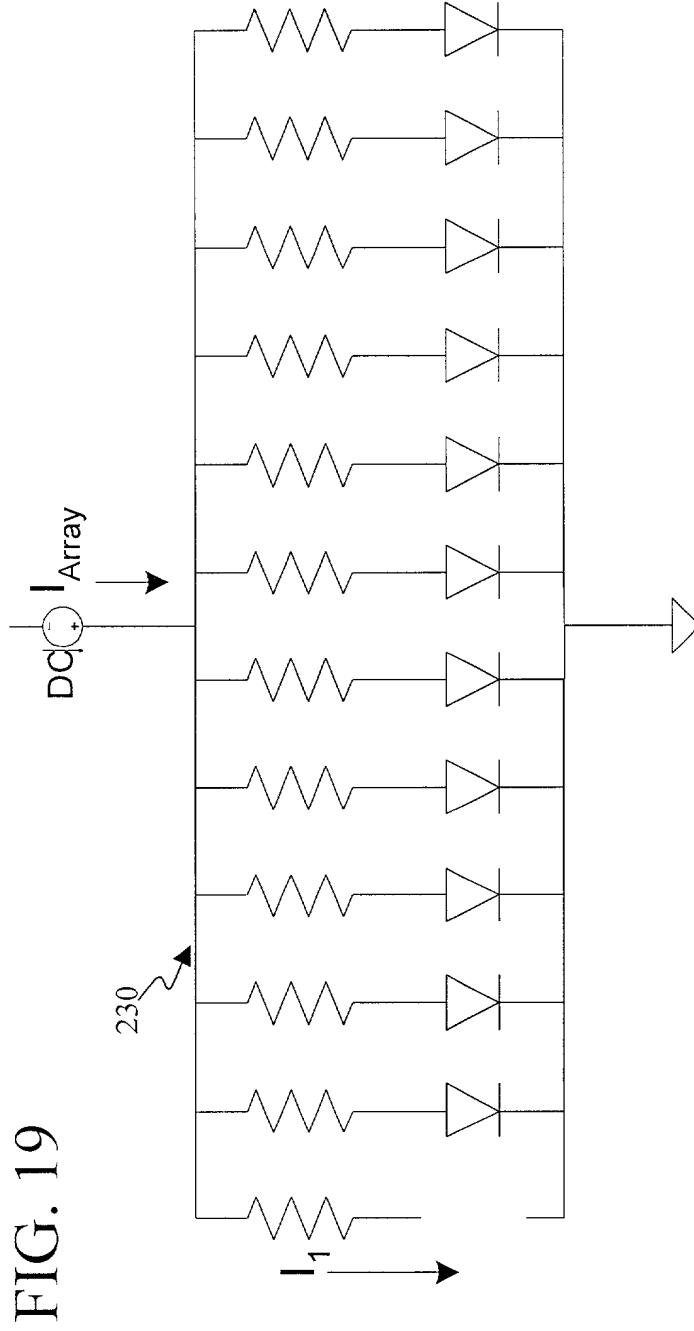


FIG. 17

FIG. 18





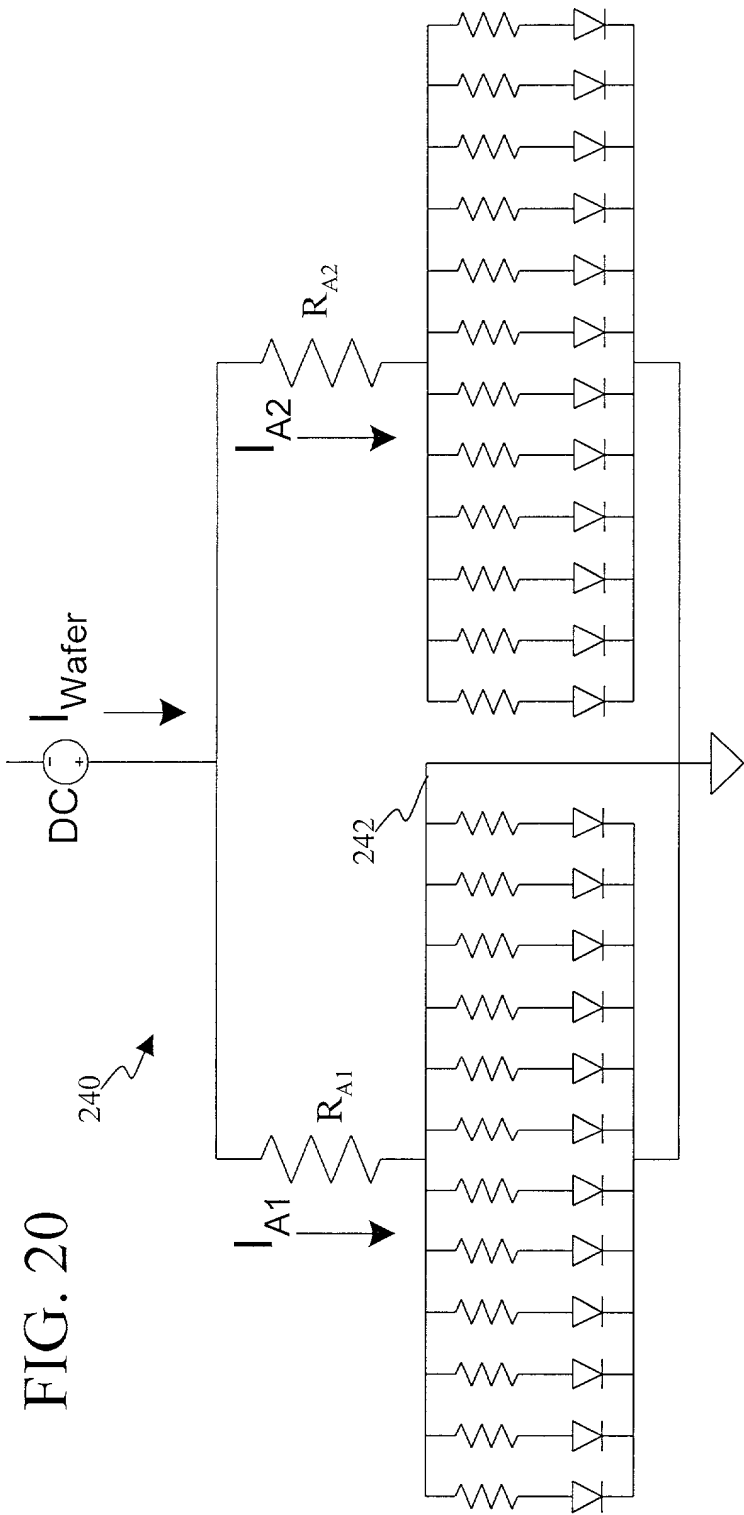


FIG. 20 is a schematic diagram of a circuit for performing whole wafer burn-in. The circuit includes a DC voltage source connected to a wafer, with current I_{Wafer} flowing into it. The circuit is divided into two main branches, 240 and 242. Branch 240 contains a resistor R_{A1} and a current source I_{A1} . Branch 242 contains a resistor R_{A2} and a current source I_{A2} . Both branches feed into a series of diodes, each preceded by a resistor. The output of the diodes is connected to a common ground.

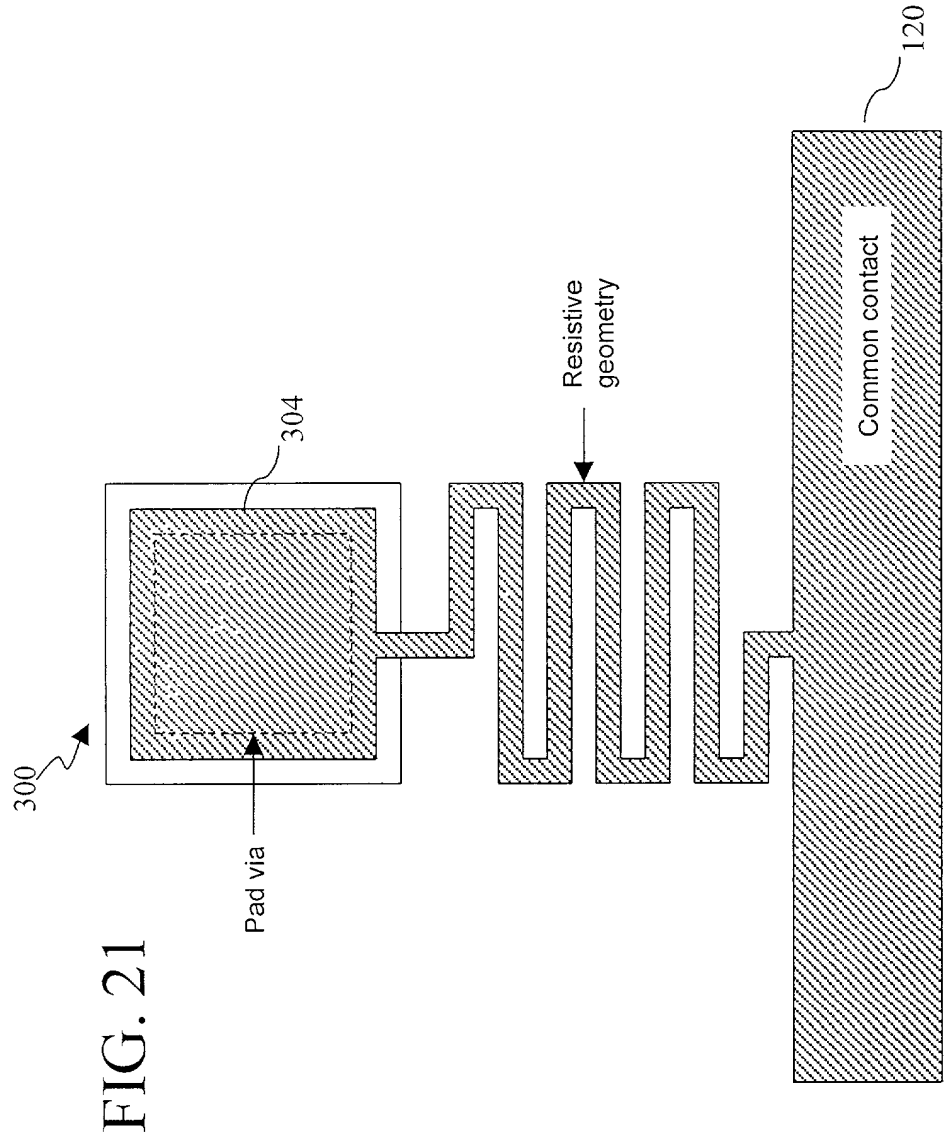


FIG. 22

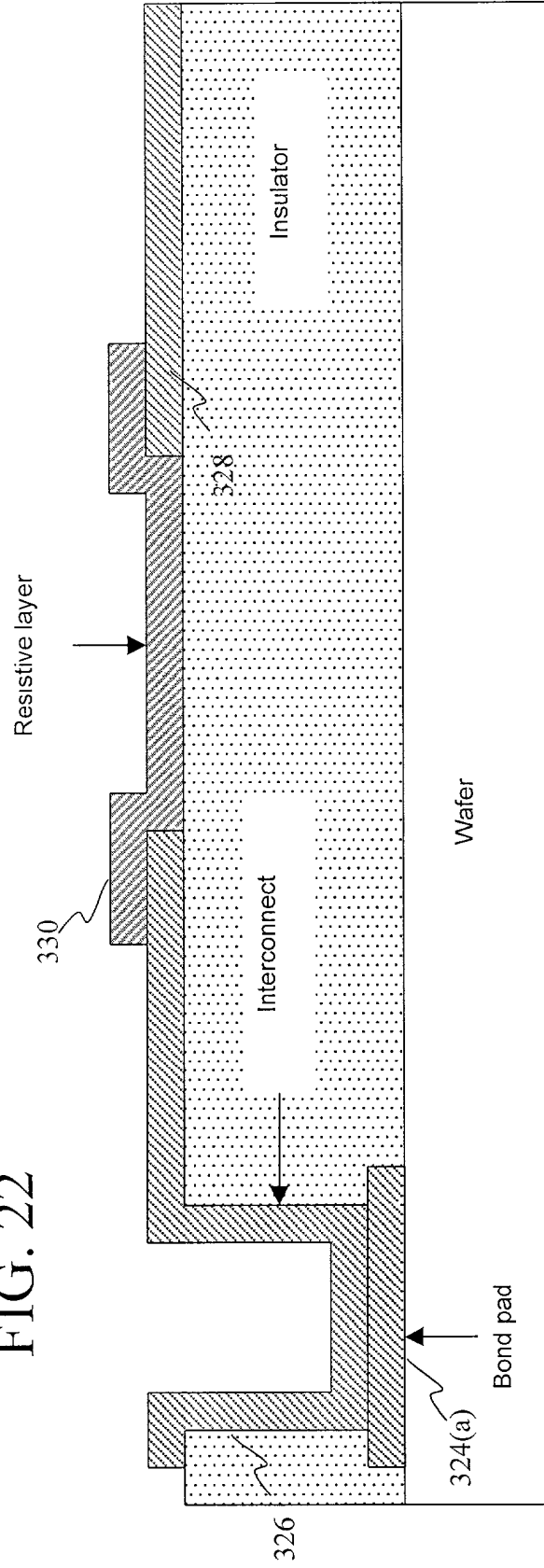


FIG. 23

